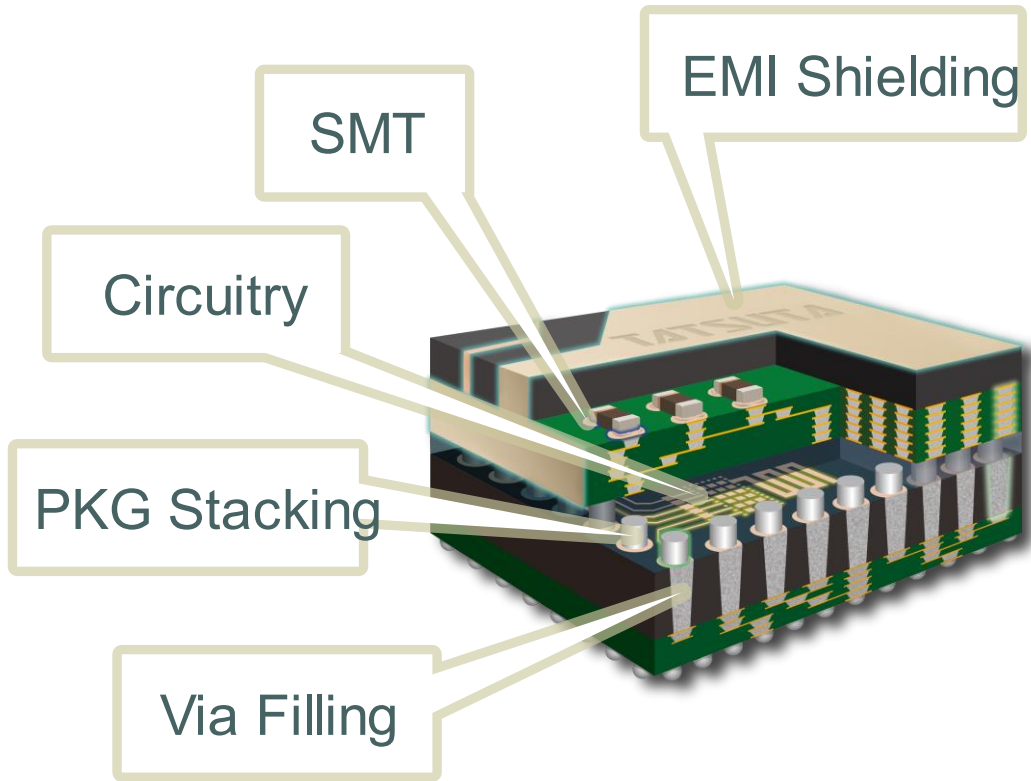


TATSUTA Advanced Paste

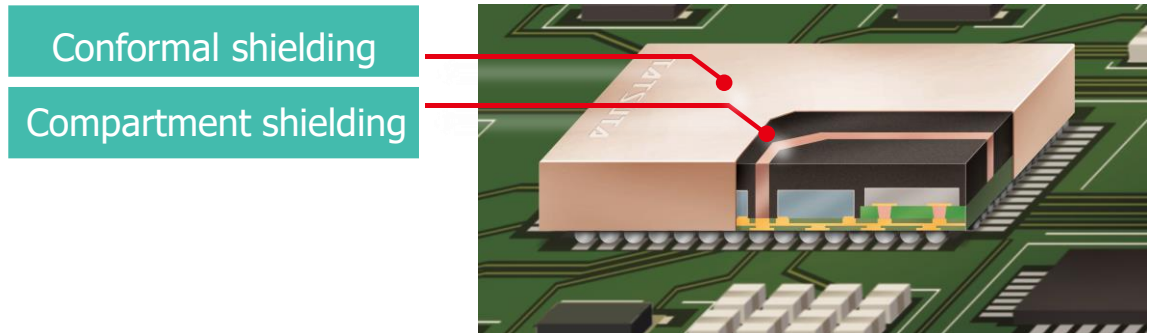
YUHON is only agent of TATSUTA in Taiwan.

Application in Semiconductor



EMI Shielding

TATSUTA have 2 lineups - spray type and print type. Spray type is for conformal EMI shielding covering package with conductive paste by spraying. Print type is for compartment EMI shielding trench filled with conductive paste by printing.



■ Main characteristic

Conformal shielding

- Excellent shielding property <over 70dB in the range of 1GHz to 10GHz under 10um thickness>
- Excellent adhesion on various material

Line up
AE5000 Series

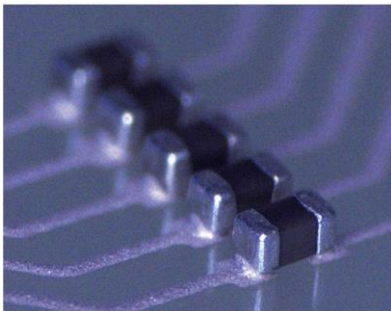
Compartment shielding

- Excellent shielding property <over 60dB in the range of 1GHz to 10GHz>
- Narrow trench wide <about 100um> can be applicable by using Vacuumed screen printing.

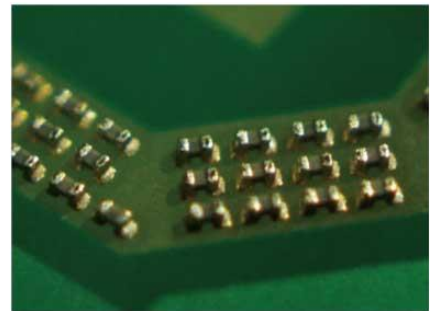
Line up
AE1244

SMT

TATSUTA paste for SMT is suitable for low heat resistance SMT application.



SMT on PET film with trace



0201 chip with SMT Paste

■ Main characteristic

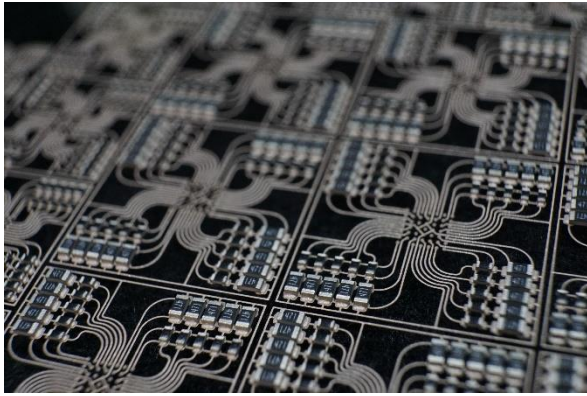
- Curable 120–160deg, C low temperature.
- Higher shear strength than solder
- Excellent adhesion on various material

Line up
AE8006

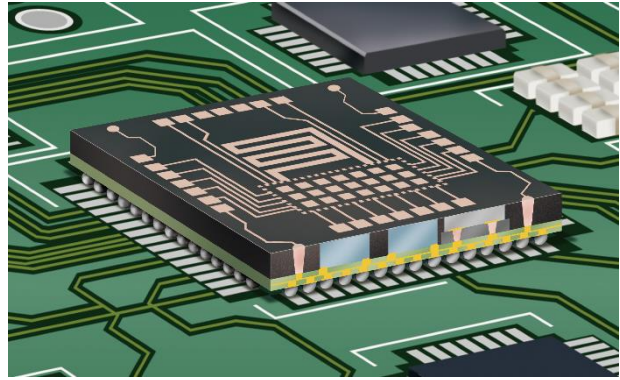
Circuitry

TATSUTA paste for circuitry is applicable for low temperature substrate. Circuitry can be formed on various materials - PET, COP, molding resin, LCP, wafer and etc.

Circuitry on glass interposer



Circuitry on PKG



■ Main characteristic

- Applicable to low temperature substrate (100deg.C x 60min)
- Excellent electroless plating property
- Easy to consist electrode
- Applicable to bendable material

Line up
SW series

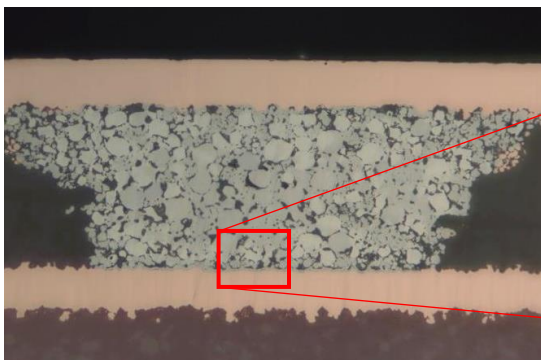
PKG Stacking

We develop functional paste for package stacking placed between packages for stable connecting and thermal release. They must sustain the evolution making semiconductors more functional and smaller.

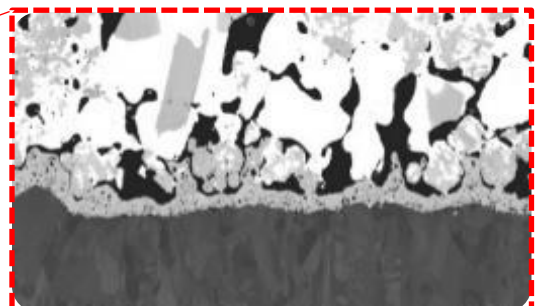
Via Filling

TATSUTA paste for via filling has long history for more than 30years. We have two Via Filling paste lineups – MP series and AE series.

MP series



IMC Layer

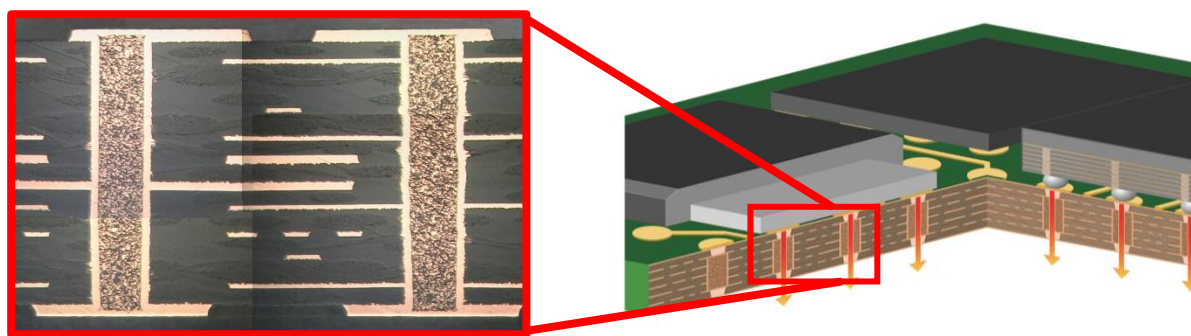


MP series is blend low-melting-point with high-melting-point powder type. This pastes alloy with Cu foil of a board at low temperature below 160deg.C through heat and press process. This alloying changes the melting point to high temperature above 260deg.C that leads to good heat reliability.

■ Main characteristic

- Stable and reliable connection by forming IMC layer on copper foil.
- High heat resistance and high thermal conductivity.

AE series



AE series is silver powder or silver coated copper powder type. Heat shrink of binder makes powders contacting each other and generate conductivity and heat release performance.

■ Main characteristic

- Void less by solvent free formulation.
- Excellent adhesion on various base materials.
- High heat resistance and high thermal conductivity.

TATSUTA is a Japanese functional paste supplier and has developed paste for semiconductor and electronics, automotive industry.

TATSUTA
www.tatsuta.com